

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

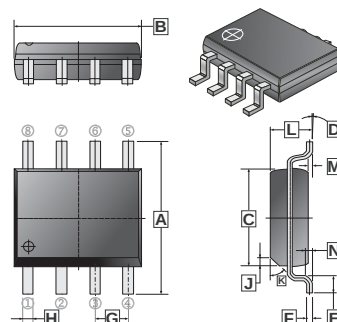
DESCRIPTION

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $R_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

FEATURES

- Low $R_{DS(on)}$ provides higher efficiency and extends battery life.
- Low thermal impedance copper leadframe SOP-8 saves board space.
- Fast switching speed.
- High performance trench technology.

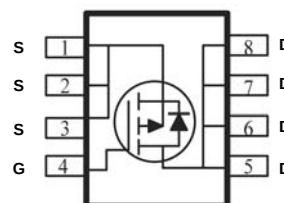
SOP-8



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	5.80	6.20	H	0.35	0.49
B	4.80	5.00	J	0.375	REF.
C	3.80	4.00	K	45°	
D	0°	8°	L	1.35	1.75
E	0.40	0.90	M	0.10	0.25
F	0.19	0.25	N	0.25	REF.
G	1.27 TYP.				

PACKAGE INFORMATION

Package	MPQ	LeaderSize
SOP-8	2.5K	13' inch



MAXIMUM RATINGS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±25	V
Continuous Drain Current ¹	I _D @ T _A = 25°C	-11.5	A
	I _D @ T _A = 70°C	-9.3	A
Pulsed Drain Current ²	I _{DM}	±50	A
Continuous Source Current (Diode Conduction) ¹	I _S	-2.1	A
Total Power Dissipation ¹	P _D @ T _A = 25°C	3.1	W
	P _D @ T _A = 70°C	2.3	W
Operating Junction & Storage Temperature Range	T _J , T _{STG}	-55 ~ 150	°C
Thermal Resistance Ratings			
Thermal Resistance Junction-Case (Max.) ¹	t ≤ 5 sec	R _{θJC}	25 °C / W
Thermal Resistance Junction-Ambient (Max.) ¹	t ≤ 5 sec	R _{θJA}	50 °C / W

Notes:

- 1 Surface Mounted on 1" x 1" FR4 Board.
- 2 Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	-30	-	-	V	$V_{GS} = 0V, I_D = -250\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	-1	-	-	V	$V_{DS} = V_{GS}, I_D = -250\mu A$
Gate-Body Leakage Current	I_{GSS}	-	-	± 100	μA	$V_{DS} = 0V, V_{GS} = \pm 25V$
Zero Gate Voltage Drain Current	I_{DSS}	-	-	-1	μA	$V_{DS} = -24V, V_{GS} = 0V$
		-	-	-5	μA	$V_{DS} = -24V, V_{GS} = 0V, T_J = 55^\circ\text{C}$
On-State Drain Current ¹	$I_{D(on)}$	-50	-	-	A	$V_{DS} = -5V, V_{GS} = -10V$
Drain-Source On-Resistance ¹	$R_{DS(ON)}$	-	-	13	m Ω	$V_{GS} = -10V, I_D = -11.5A$
		-	-	19		$V_{GS} = -4.5V, I_D = -9.3A$
Forward Transconductance ¹	g_{fs}	-	29	-	S	$V_{DS} = -15V, I_D = -11.5A$
Diode Forward Voltage	V_{SD}	-	-0.8	-	V	$I_S = 2.5A, V_{GS} = 0V$
Dynamic ²						
Total Gate Charge	Q_g	-	25	-	nC	$I_D = -11.5A$ $V_{DS} = -15V$ $V_{GS} = -5V$
Gate-Source Charge	Q_{gs}	-	11	-		
Gate-Drain Charge	Q_{gd}	-	17	-		
Input Capacitance	C_{iss}	-	2300	-	pF	$V_{DS} = -15V$ $V_{GS} = 0V$ $f = 1\text{MHz}$
Output Capacitance	C_{oss}	-	600	-		
Reverse Transfer Capacitance	C_{rss}	-	300	-		
Turn-On Delay Time	$T_{d(on)}$	-	15	-	nS	$V_{DD} = -15V$ $I_D = -1A$ $V_{GEN} = -10V$ $R_L = 6\Omega$
Rise Time	T_r	-	13	-		
Turn-Off Delay Time	$T_{d(off)}$	-	100	-		
Fall Time	T_f	-	54	-		

Notes:

- 1 Pulse test : $PW \leq 300\mu s$ duty cycle $\leq 2\%$.
- 2 Guaranteed by design, not subject to production testing.

Typical Electrical Characteristics (P-Channel)

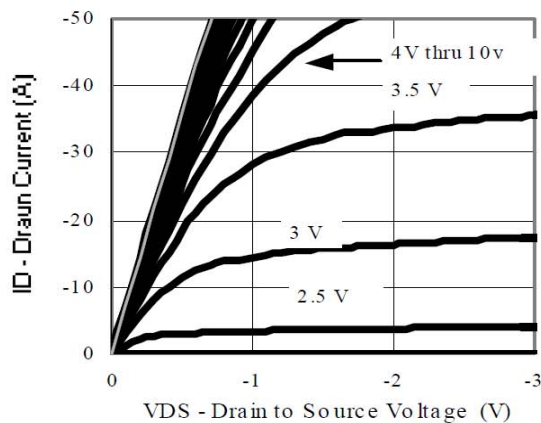


Figure 1. On-Region Characteristics

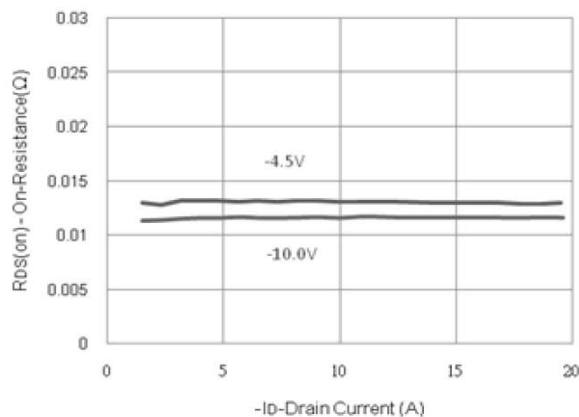


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

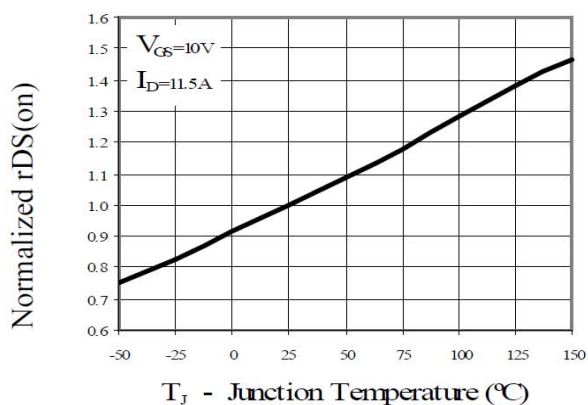


Figure 3. On-Resistance Variation with Temperature

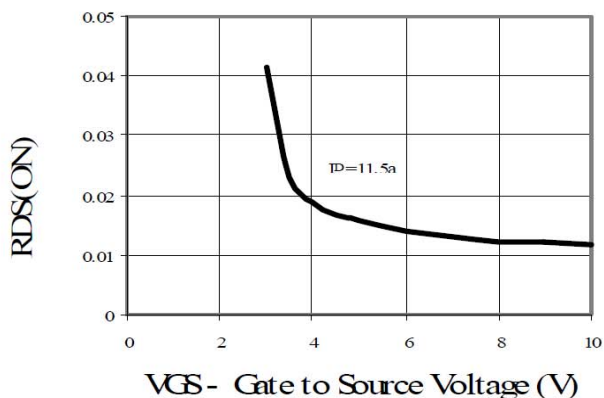


Figure 4. On-Resistance with Gate to Source Voltage

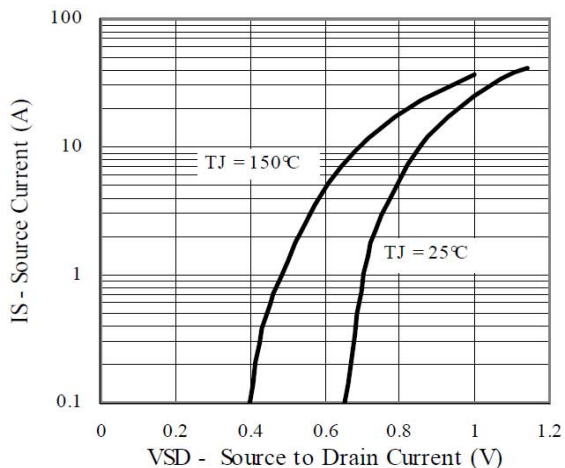


Figure 5. Transfer Characteristics

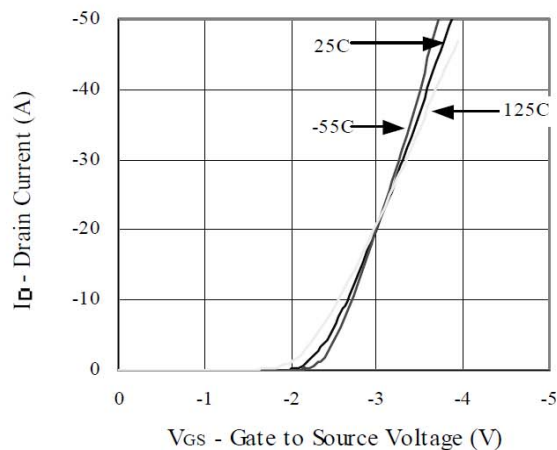


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Electrical Characteristics (P-Channel)

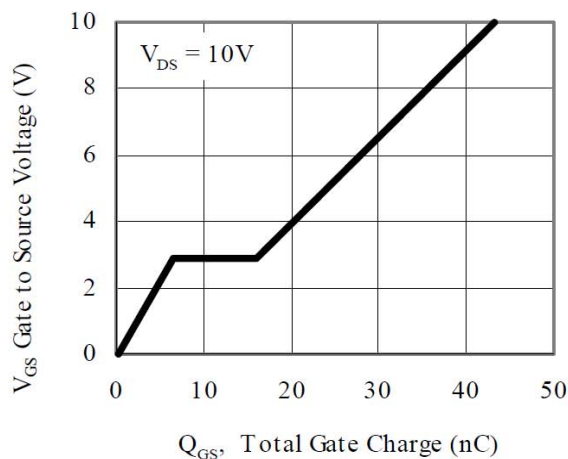


Figure 7. Gate Charge Characteristics

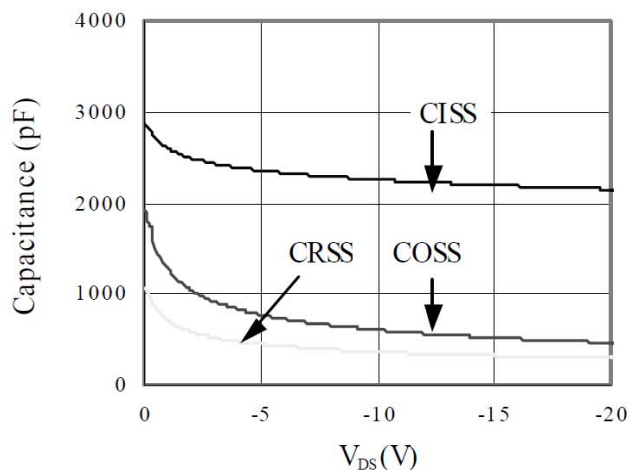


Figure 8. Capacitance Characteristics

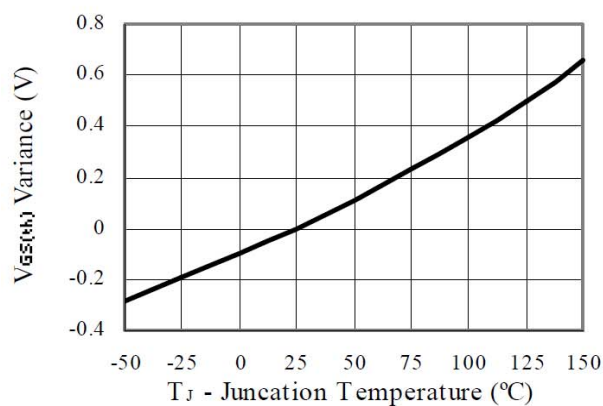


Figure 9. Maximum Safe Operating Area

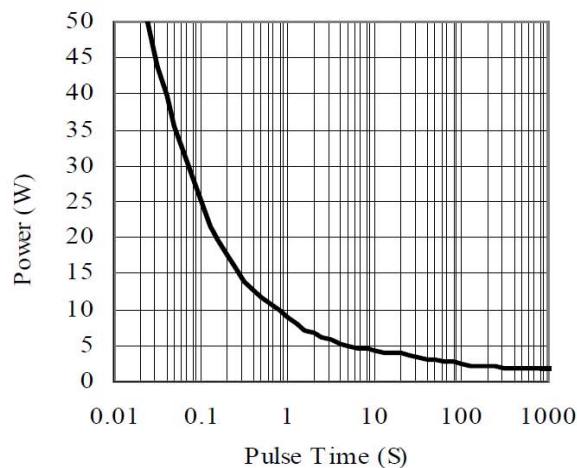


Figure 10. Single Pulse Maximum Power Dissipation

Normalized Thermal Transient Junction to Ambient

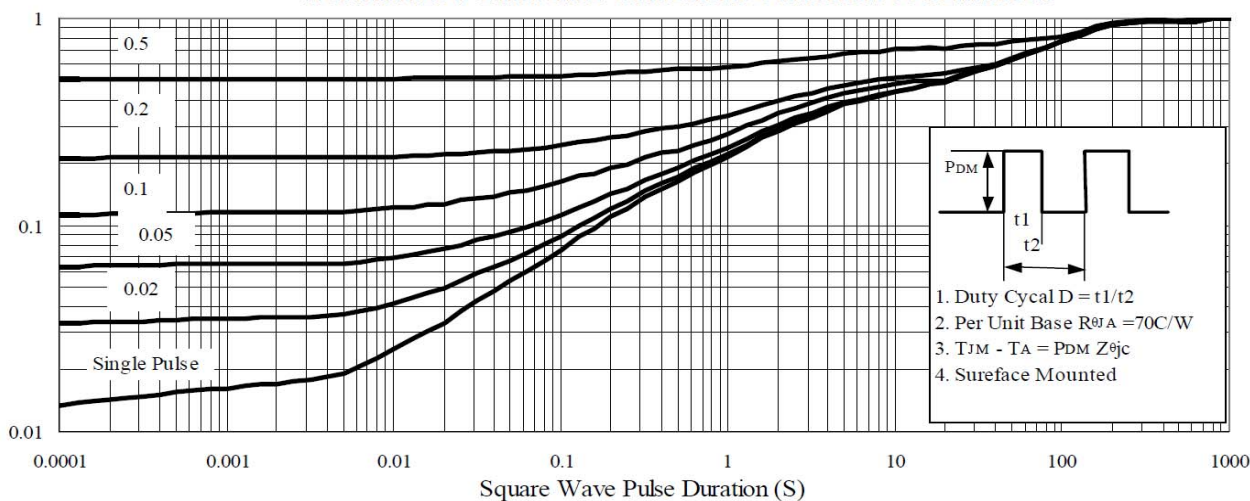


Figure 11. Transient Thermal Response Curve